

L Number	Hits	Search Text	DB	Time stamp
-	1	(electrolytic near4 plating) and (feeder adj film)	USPAT;	2003/11/28
-	3227	(electrolytic near4 plating) and substrate	US-PGPUB	12:46
-	4669	electrolytic near4 plating	USPAT;	2002/11/22
-	3142	electrolytic adj plating	US-PGPUB	11:07
-	3142	electrolytic adj plating	USPAT;	2002/11/22
-	2452	(electrolytic adj plating) and (substrate or semiconductor)	US-PGPUB	13:52
-	37	tonami.in.	USPAT;	2002/11/22
-	3	tonami.in. and Yoshiyuki	US-PGPUB	13:52
-	37	tonami.in.	USPAT;	2002/11/22
-	485	tonami.in.	US-PGPUB	13:52
-	0	tonami.in. and yoshiyuki	USPAT;	2002/11/22
-	34	tonami.in. and yoshiyuki	US-PGPUB	13:53
-	2143	216/13.ccls. or 216/18.ccls.	USPAT;	2002/11/22
-	23	(216/13.ccls. or 216/18.ccls.) and 216/40.ccls.	US-PGPUB;	14:06
-	1	((216/13.ccls. or 216/18.ccls.) and 216/40.ccls.) and 216/100.ccls.	EPO; JPO;	2002/11/22
-	147	(216/13.ccls. or 216/18.ccls.) and 205/\$.ccls.	DERWENT;	14:06
-	0	((216/13.ccls. or 216/18.ccls.) and 205/\$.ccls.) and 216/40.ccls.	IBM TDB	2002/11/22
-	11	((216/13.ccls. or 216/18.ccls.) and 205/\$.ccls.) and 216/100.ccls.	USPAT;	14:15
-	35	(205/80.ccls. or 205/123.ccls. or 205/125.ccls. or 205/223.ccls.) and taper\$4	US-PGPUB;	2002/11/22
-	1	((205/80.ccls. or 205/123.ccls. or 205/125.ccls. or 205/223.ccls.) and taper\$4) and lift-off	EPO; JPO;	14:16
-	118	205/80.ccls.	DERWENT;	2002/11/22
-	121	205/169.ccls.	IBM TDB	15:37
			USPAT;	2002/11/22
			US-PGPUB	15:10

-	0	(205/80, 123, 157, "169" and "223").ccls. and (electrolytic adj plating adj electrode)	USPAT; US-PGPUB	2002/11/22 15:40
-	0	(205/80,123,157,169,223).ccls. and (electrolytic adj plating adj electrode)	USPAT; US-PGPUB	2002/11/22 15:41
-	0	c25d005/\$.ipc. and (electrolytic near4 plating) and (feeder adj film)	JPO; DERWENT	2002/11/22 16:46
-	0	c25d005/\$.ipc.	JPO; DERWENT	2002/11/22 16:45
-	18607	c25d005/\$.ipc.	JPO; DERWENT	2002/11/22 16:45
-	0	c25d005/\$.ipc. and (electrolytic near4 plating) and (feeder adj film)	JPO; DERWENT	2002/11/22 16:46
-	651	c25d005/\$.ipc. and (electrolytic near4 plating)	JPO; DERWENT	2002/11/22 18:46
-	55	(c25d005/\$.ipc. and (electrolytic near4 plating)) and (feed\$2 or electrode or wire\$4 or base) and (cu or copper or ti or titanium)	JPO; DERWENT	2002/11/22 16:51
-	285	(c25d005/\$.ipc. and (electrolytic near4 plating)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4)	JPO; DERWENT	2002/11/22 17:38
-	28	(c25d005/\$.ipc. and (electrolytic near4 plating)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)	JPO; DERWENT	2002/11/22 18:41
-	3874	(205/\$ or 216/\$).ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)	USPAT; US-PGPUB	2002/11/22 18:20
-	1492	205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)	USPAT; US-PGPUB	2002/11/22 18:24
-	1410	(205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)) and @ad<20010117	USPAT; US-PGPUB	2002/11/22 18:23
-	1297	205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)	USPAT; US-PGPUB	2002/11/22 18:28
-	149	(205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wire\$4 near7 form\$8)	USPAT; US-PGPUB	2002/11/22 18:32
-	168	(205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wir\$4 near7 form\$5)	USPAT; US-PGPUB	2002/11/22 18:34
-	43	(205/\$.ccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and ((wire or wiring) near7 (formation or pattern or fabrication))	USPAT; US-PGPUB	2002/11/27 09:52
-	1312	(205/80, 123, 125, 223, 157).ccls.	USPAT; US-PGPUB	2002/11/22 18:40
-	1868	(216/13,18,40,100).ccls.	USPAT; US-PGPUB	2002/11/22 18:41
-	3103	((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)	USPAT; US-PGPUB	2002/11/22 18:41
-	1015	((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)	USPAT; US-PGPUB	2002/11/22 18:43
-	964	((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117	USPAT; US-PGPUB	2002/11/22 18:44
-	99	(((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/23 15:04

-	99	(((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/23 11:59
-	99	(((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/26 18:55
-	1	4866008.pn.	USPAT; US-PGPUB	2002/11/23 17:09
-	103	205/186.ccls.	USPAT; US-PGPUB	2002/11/27 09:45
-	361	(((((205/123,125,223,157,186).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic\$4 or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/26 18:54
-	99	(((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/26 18:59
-	263	(((((205/123,125,223,157,186).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic\$4 or electrodeposit\$4)) not (((((205/80,123,125,223,157).ccls.) or ((216/13,18,40,100).ccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating))	USPAT; US-PGPUB	2002/11/26 18:56
-	270	(205/186,123,125,223,157).ccls. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117 and ((electrolytic near plating) or electroplating or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/27 10:42
-	19	205/186.ccls. and ((feed\$4 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (partial\$4 or mask or pattern))	USPAT; US-PGPUB	2002/11/27 10:34
-	3	"2000008247"	JPO; DERWENT	2002/11/27 10:41
-	22685	h011021/3205.ipc.	JPO; DERWENT	2002/11/27 10:41
-	47	h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	JPO; DERWENT	2002/11/27 15:48
-	1	04262536.pn.	DERWENT	2002/11/27 14:29
-	1	"04262536"	DERWENT	2002/11/27 14:30
-	2	"04262536"	JPO; DERWENT	2002/11/27 15:10
-	1	5550068.pn.	USPAT; US-PGPUB	2002/11/27 15:10

-	0	(205/186,123,125,223,157). and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/27 15:51
-	283	(205/186,123,125,223,157).cccls. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/27 15:56
-	384	(h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	JPO; DERWENT	2002/11/27 15:55
-	337	((h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) not (h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4))	JPO; DERWENT	2002/11/27 15:53
-	28	((h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) not (h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) and ((remove or etch) near7 (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed))	JPO; DERWENT	2002/11/27 16:18
-	1	5550068.pn.	USPAT; US-PGPUB	2002/11/27 16:18
-	5707	yoshiyuki.in.	USPAT; US-PGPUB	2003/03/28 10:42
-	3	yoshiyuki.in. and tonami	USPAT; US-PGPUB	2003/03/28 10:42
-	9026	yoshihiro.in.	USPAT; US-PGPUB	2003/03/28 10:44
-	13	yoshihiro.in. and koshido	USPAT; US-PGPUB	2003/03/28 10:44
-	15	(yoshiyuki.in. and tonami) or (yoshihiro.in. and koshido)	USPAT; US-PGPUB	2003/03/28 10:44
-	154	(205/\$.cccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wire\$4 near7 form\$6)	USPAT; US-PGPUB	2003/03/31 16:39
-	1311	205/80.cccls. or 205/123.cccls. or 205/125.cccls. or 205/223.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/31 18:09
-	1	5550068.pn.	USPAT; US-PGPUB	2003/07/11 14:24
-	2	"06260482"	JPO; DERWENT	2003/07/11 17:42
-	20	(438/727,643,648,653).cccls. and (diffusion near3 prevent\$4)	JPO; DERWENT	2003/07/11 17:50

-	20	((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117	JPO; DERWENT	2003/07/11 17:50
-	509	(438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)	USPAT; US-PGPUB	2003/07/11 17:49
-	0	((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117	JPO; DERWENT	2003/07/11 17:50
-	320	((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117	USPAT; US-PGPUB	2003/07/11 17:50
-	223	((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117) and tungsten	USPAT; US-PGPUB	2003/07/11 17:50
-	0	((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117) and (diffusion near3 prevent\$4 near3 tungsten)	JPO; DERWENT	2003/07/11 17:51
-	9	((438/727,643,648,653).ccls. and (diffusion near3 prevent\$4)) and @ad<20000117) and (diffusion near3 prevent\$4 near3 tungsten)	USPAT; US-PGPUB	2003/07/12 10:07
-	1	5550068.pn.	USPAT; US-PGPUB	2003/07/12 10:07
-	4974	((electro adj plating) or electroplating) same (gold or au)	USPAT; US-PGPUB	2003/11/28 12:49
-	6001	((electro adj plating) or electroplating) same (line or circuit)	USPAT; US-PGPUB	2003/11/28 12:50
-	1514	((electro adj plating) or electroplating) same (gold or au)) and ((electro adj plating) or electroplating) same (line or circuit))	USPAT; US-PGPUB	2003/11/28 12:49
-	2803	((electro adj plating) or electroplating) with (gold or au)	USPAT; US-PGPUB	2003/11/28 12:57
-	2956	((electro adj plating) or electroplating)with (line or circuit)	USPAT; US-PGPUB	2003/11/28 12:53
-	471	((electro adj plating) or electroplating) with (gold or au)) and ((electro adj plating) or electroplating)with (line or circuit))	USPAT; US-PGPUB	2003/11/28 12:51
-	140	((electro adj plating) or electroplating) with (gold or au)) and ((electro adj plating) or electroplating)with (line or circuit))) and (diffusion or barrier)	USPAT; US-PGPUB	2003/11/28 12:52
-	2034	((electro adj plating) or electroplating) near7 (gold or au)	USPAT; US-PGPUB	2003/11/28 12:53
-	1966	((electro adj plating) or electroplating) near7 (line or circuit)	USPAT; US-PGPUB	2003/11/28 12:54
-	215	((electro adj plating) or electroplating) near7 (gold or au)) and ((electro adj plating) or electroplating) near7 (line or circuit))	USPAT; US-PGPUB	2003/11/28 15:43
-	365	((h011021/\$.ipc. or c23c016/\$.ipc.) and ((electro adj plating) or electroplating) and (gold or au)	JPO; DERWENT	2003/11/28 12:58
-	101	((h011021/\$.ipc. or c23c016/\$.ipc.) and ((electro adj plating) or electroplating) and (gold or au) and (line or circuit)	JPO; DERWENT	2003/11/28 13:19
-	23	((h011021/\$.ipc. or c23c016/\$.ipc.) and ((electro adj plating) or electroplating) and (gold or au) and (line or circuit)) and (diffusion or adhesi\$4)	JPO; DERWENT	2003/11/28 13:21
-	15	((electro adj plating) or electroplating) near7 (gold or au)) and ((electro adj plating) or electroplating) near7 (line or circuit))) and (wet near etch\$4)	USPAT; US-PGPUB	2003/11/28 15:43

-	11	(((electro adj plating) or electroplating) near7 (gold or au)) and ((electro adj plating) or electroplating) near7 (line or circuit))) and (wet near etch\$4)) and @ad<20000117	USPAT; US-PGPUB	2003/11/28 15:44
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